

Overview of index of products and services

1	Materials	4	Inspection and test systems
2	Manufacturing processes	5	Devices
3	Electronics assembly and packaging, system integration	6	Applications
		7	Services

Index of products and services

- | | | | |
|--------------------------------|-----------------------------------------------|---------------------------------|---------------------------------------|
| 1 | Materials | 2.2 | Digital printing |
| 1.1 | Substrates | <input type="checkbox"/> 2.2.1 | Ink-jet printing |
| <input type="checkbox"/> 1.1.1 | Plastic films | <input type="checkbox"/> 2.2.2 | Other digital printing |
| <input type="checkbox"/> 1.1.2 | Metal foils | 2.3 | Other printing processes |
| <input type="checkbox"/> 1.1.3 | Paper | <input type="checkbox"/> 2.3.1 | Microcontact printing |
| <input type="checkbox"/> 1.1.4 | Glass | <input type="checkbox"/> 2.3.2 | Nano imprint |
| <input type="checkbox"/> 1.1.5 | Textiles | 2.4 | Vacuum processes |
| <input type="checkbox"/> 1.1.6 | Other substrates | <input type="checkbox"/> 2.4.1 | Evaporation |
| 1.2 | Conductors | <input type="checkbox"/> 2.4.2 | Sputtering |
| <input type="checkbox"/> 1.2.1 | Organic conductors | <input type="checkbox"/> 2.4.3 | Organic vapor phase deposition (OVPD) |
| <input type="checkbox"/> 1.2.2 | Inorganic conductors | <input type="checkbox"/> 2.4.4 | Other vacuum processes |
| <input type="checkbox"/> 1.2.3 | Nano materials | <input type="checkbox"/> 2.5 | Photolithography |
| <input type="checkbox"/> 1.2.4 | Carbon nanotubes | 2.6 | Laser processes |
| <input type="checkbox"/> 1.2.5 | Graphene | <input type="checkbox"/> 2.6.1 | Laser ablation |
| <input type="checkbox"/> 1.2.6 | Hybrid conductors | <input type="checkbox"/> 2.6.2 | Laser transfer |
| 1.3 | Semiconductors | 2.7 | Coating technologies |
| <input type="checkbox"/> 1.3.1 | Polymer semiconductors | <input type="checkbox"/> 2.7.1 | Spin coating |
| <input type="checkbox"/> 1.3.2 | Small molecule semiconductors | <input type="checkbox"/> 2.7.2 | Dip coating |
| <input type="checkbox"/> 1.3.3 | Inorganic semiconductors | <input type="checkbox"/> 2.7.3 | Blade coating |
| <input type="checkbox"/> 1.3.4 | Nano materials semiconductors | <input type="checkbox"/> 2.7.4 | Other coating techniques |
| <input type="checkbox"/> 1.3.5 | Carbon nanotube semiconductors | 2.8 | Material processing |
| <input type="checkbox"/> 1.3.6 | Hybrid semiconductors | <input type="checkbox"/> 2.8.1 | Dispersion technologies |
| 1.4 | Dielectrics | <input type="checkbox"/> 2.8.2 | Other material processing |
| <input type="checkbox"/> 1.4.1 | Organic dielectrics | 2.9 | Light induced processing |
| <input type="checkbox"/> 1.4.2 | Inorganic dielectrics | <input type="checkbox"/> 2.9.1 | IR drying |
| <input type="checkbox"/> 1.4.3 | Nano materials | <input type="checkbox"/> 2.9.2 | UV curing |
| <input type="checkbox"/> 1.4.4 | Hybrid dielectrics | <input type="checkbox"/> 2.9.3 | Laser processes |
| 1.5 | Encapsulation materials, resins and adhesives | 2.10 | Dosing and mixing technology |
| <input type="checkbox"/> 1.5.1 | Thin film encapsulation | <input type="checkbox"/> 2.10.1 | Pumps |
| <input type="checkbox"/> 1.5.2 | Polymer film encapsulation | <input type="checkbox"/> 2.10.2 | Other dosing and mixing technologies |
| <input type="checkbox"/> 1.5.3 | Metal encapsulation | 2.11 | Encapsulation |
| <input type="checkbox"/> 1.5.4 | Glass encapsulation | <input type="checkbox"/> 2.11.1 | Thin film encapsulation |
| <input type="checkbox"/> 1.5.5 | Resins and adhesives | <input type="checkbox"/> 2.11.2 | Polymer film encapsulation |
| <input type="checkbox"/> 1.6 | Other materials | <input type="checkbox"/> 2.11.3 | Metal encapsulation |
| | | <input type="checkbox"/> 2.11.4 | Glass encapsulation |
| | | <input type="checkbox"/> 2.11.5 | Other encapsulation processes |
| 2 | Manufacturing processes | <input type="checkbox"/> 2.12 | Clean room technology |
| 2.1 | Mass patterning techniques | <input type="checkbox"/> 2.13 | Roll-to-roll processing |
| <input type="checkbox"/> 2.1.1 | Gravure printing | <input type="checkbox"/> 2.14 | Other manufacturing processes |
| <input type="checkbox"/> 2.1.2 | Offset printing | | |
| <input type="checkbox"/> 2.1.3 | Flexographic printing | | |
| <input type="checkbox"/> 2.1.4 | Screen printing | | |
| <input type="checkbox"/> 2.1.5 | Other mass patterning techniques | | |

Index of products and services

info@lopec.com, Tel. +49 89 949-20225

Messe München GmbH, Am Messesee 2, 81829 München, Germany

3 Electronics assembly and packaging, system integration

- 3.1 Electronics assembly and packaging
 - 3.1.1 Flip chip
 - 3.1.2 Other electrical contacting
- 3.2 Lamination
- 3.3 System integration
- 3.4 Hybrid systems (polytronics)

4 Inspection and test systems

- 4.1 Electrical characterization
- 4.2 Physical/optical characterization
- 4.3 Chemical characterization
- 4.4 Simulation/circuit optimization
- 4.5 Lifetime testing
- 4.6 Quality/process control
- 4.7 Environmental testing
- 4.8 Other inspection and test systems

5 Devices

- 5.1 Transistors
- 5.2 Diodes
- 5.3 Passive components
 - 5.3.1 Capacitors
 - 5.3.2 Resistors
 - 5.3.3 Other passives
- 5.4 Integrated circuits
- 5.5 Displays
 - 5.5.1 OLED
 - 5.5.2 Electrophoretic displays
 - 5.5.3 Electrochromic displays
 - 5.5.4 Electroluminescent displays
 - 5.5.5 LCD
 - 5.5.6 Electrowetting
 - 5.5.7 Other displays
- 5.6 Photovoltaic cells
 - 5.6.1 Organic photovoltaics
 - 5.6.2 Hybrid photovoltaics
 - 5.6.3 Inorganic photovoltaics

5.7 Sensors

- 5.7.1 Photodiodes
- 5.7.2 Pressure sensors
- 5.7.3 Temperature sensors
- 5.7.4 Biomedical sensors
- 5.7.5 Gas sensors
- 5.7.6 Touch sensors
- 5.7.7 Other sensors
- 5.8 Memory elements
- 5.9 Antennas
- 5.10 Batteries
- 5.11 Components for hybrid systems
- 5.12 Other devices

6 Applications

- 6.1 TFT backplanes
- 6.2 Displays
- 6.3 Sensors
- 6.4 Smart systems
- 6.5 RFID
- 6.6 Solar cells
- 6.7 Smart textiles
- 6.8 Speakers
- 6.9 Lighting
- 6.10 Other applications

7 Services

- 7.1 Consulting
- 7.2 R&D funding program management
- 7.3 R&D/Research & Development
- 7.4 Prototyping
- 7.5 Manufacturing
- 7.6 Venture and equity capitalization
- 7.7 Professional and trade associations
- 7.8 Technical books, technical journals, technical publishers
- 7.9 Other services